

REVISIONS				
REV.	ECN	DESCRIPTION	DATE	APPROVED
A		PROPOSAL	APR 29.11	A.G
B		ADD THE THICKNESS DIM AND TRACE KEEP OUT AREA OF THE PCB	AUG 07.11	A.G
C		MODIFY THE DIMENSION BETWEEN PCB AND BEZEL	AUG 15.11	A.G
D		ADD 2X8 OPTION	JUL 04.12	J.SI

MATERIAL:

CAGE - PRESS FIT:
COPPER ALLOY

PLATING:
SEE AMPHENOL PART NUMBER
CONFIGURATION FOR OPTIONS.

CONNECTOR - PRESS FIT

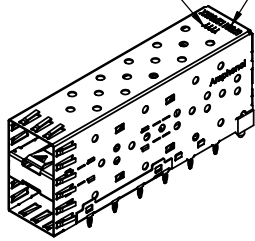
PLASTIC HOUSING:
LIQUID CRYSTAL POLYMER (LCP),
FLAMMABILITY RATING UL94-0.

CONTACTS:
PHOSPHOR BRONZE
PLATING OPTION:
SEE AMPHENOL PART NUMBER
CONFIGURATION FOR OPTIONS.

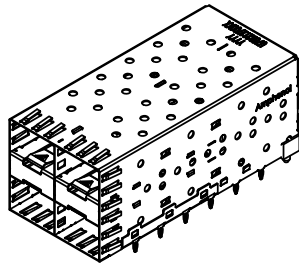
PACKAGING:
TRAY PACKAGING.

TEMPERATURE RANGE:
-40°C TO +85°C

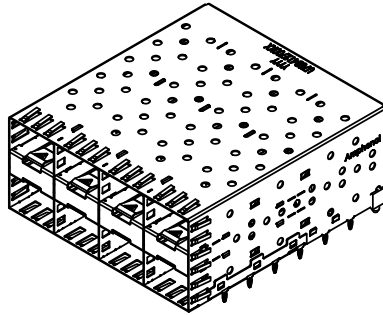
DATE CODE
PART NUMBER
(LAST DIGIT INDICATING
PACKAGING TYPE,
NOT PRINTED ON THE PART)



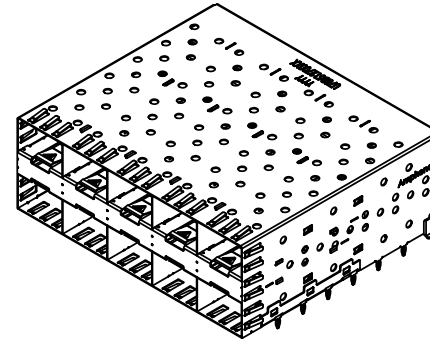
UE78-B1127-00XX1



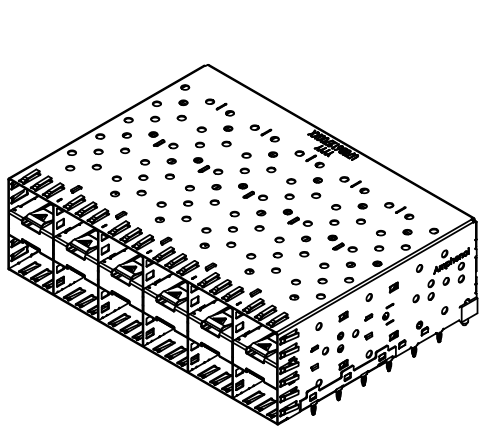
UE78-B2127-00XX1



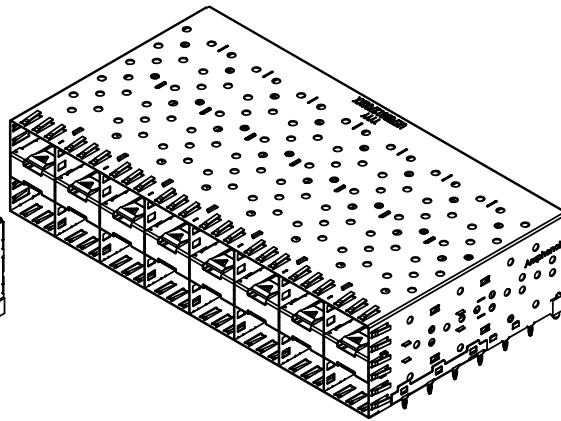
UE78-B4127-00XX1



UE78-B5127-00XX1



UE78-B6127-00XX1



UE78-B8127-00XX1

AMPHENOL PART NUMBER CONFIGURATION

UE78-B X 1 27-00 X X 1

E=ROHS COMPLIANT

NUMBER OF PORTS

- 1 = 2X1
- 2 = 2X2
- 4 = 2X4
- 5 = 2X5
- 6 = 2X6
- 8 = 2X8

PACKAGING

- 1 = TRAY PACKAGING

CAGE PLATING

- 2 = NICKEL PLATING
- 3 = MATTE TIN PLATING

PRESS FIT CONNECTOR PLATING

- 3 = 30 μ" MIN. GOLD ON MATING AREA
- 150-300 μ" MATTE TIN ON TERMINATION
- 6 = 15 μ" MIN. GOLD ON MATING AREA
- 150-300 μ" MATTE TIN ON TERMINATION



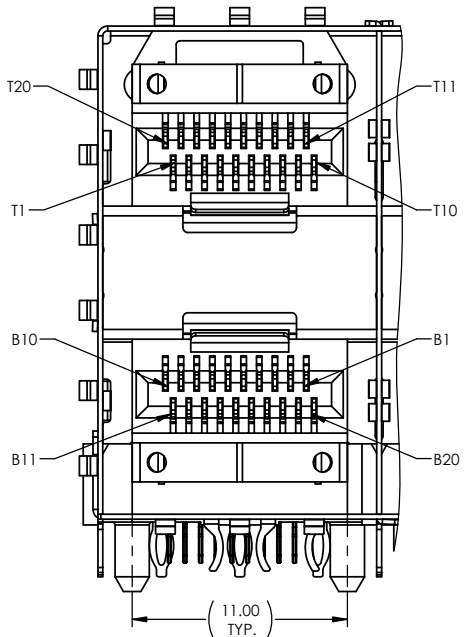
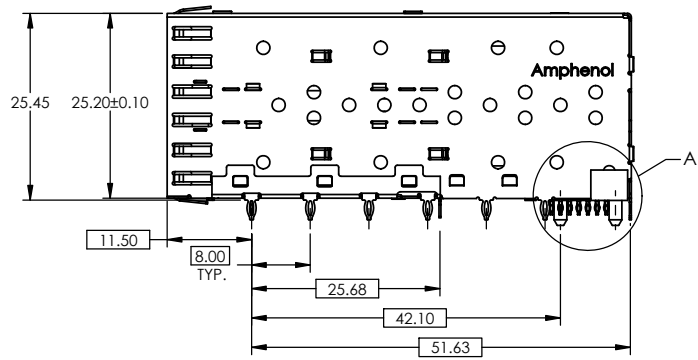
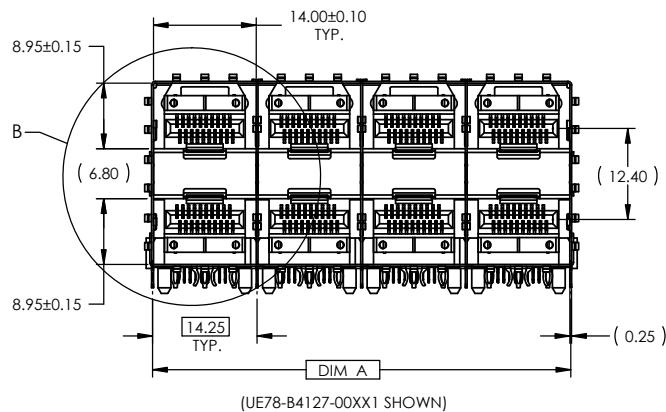
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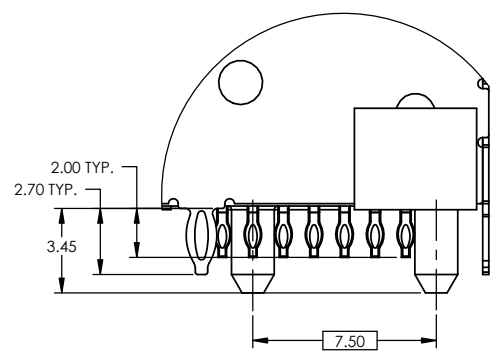
UNLESS OTHERWISE SPECIFIED DIMENSIONS ARE IN MILLIMETERS TOLERANCES ARE: DECIMALS X.X ± 0.25 X.XX ± 0.15 MATERIAL AND FINISH N/A REF. X CODE IDENT. NO. 03554	APPROVALS	DATE	Amphenol Canada Corp. SFF 2XN STACKED COMBO WITH DOUBLE BEND LATCH	
	DRAWN MIKE.H	APR 29.11		
	DESIGNED J.SI	APR 29.11		
	CHECKED J.SI	APR 29.11		
	GA APPD		SIZE A3	DWG. NO. P-UE78-BX127-00XX1
	E APPD		SCALE 2:1	PROJECT
	DWG APPD A.GREEN	APR 29.11		SHEET 1 OF 4

REVISIONS

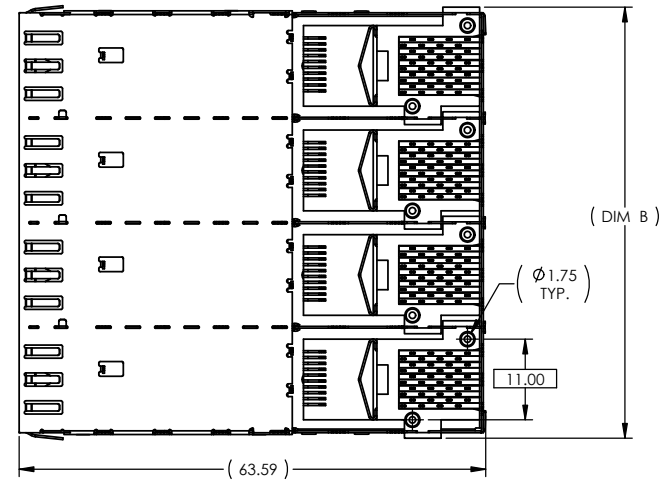
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D		ADD 2XB OPTION	JUL 04.12	J.SI



DETAIL B
SCALE 4 : 1
**TYPICAL PIN ASSIGNMENT
ON MATING AREA**



DETAIL A
SCALE 5 : 1



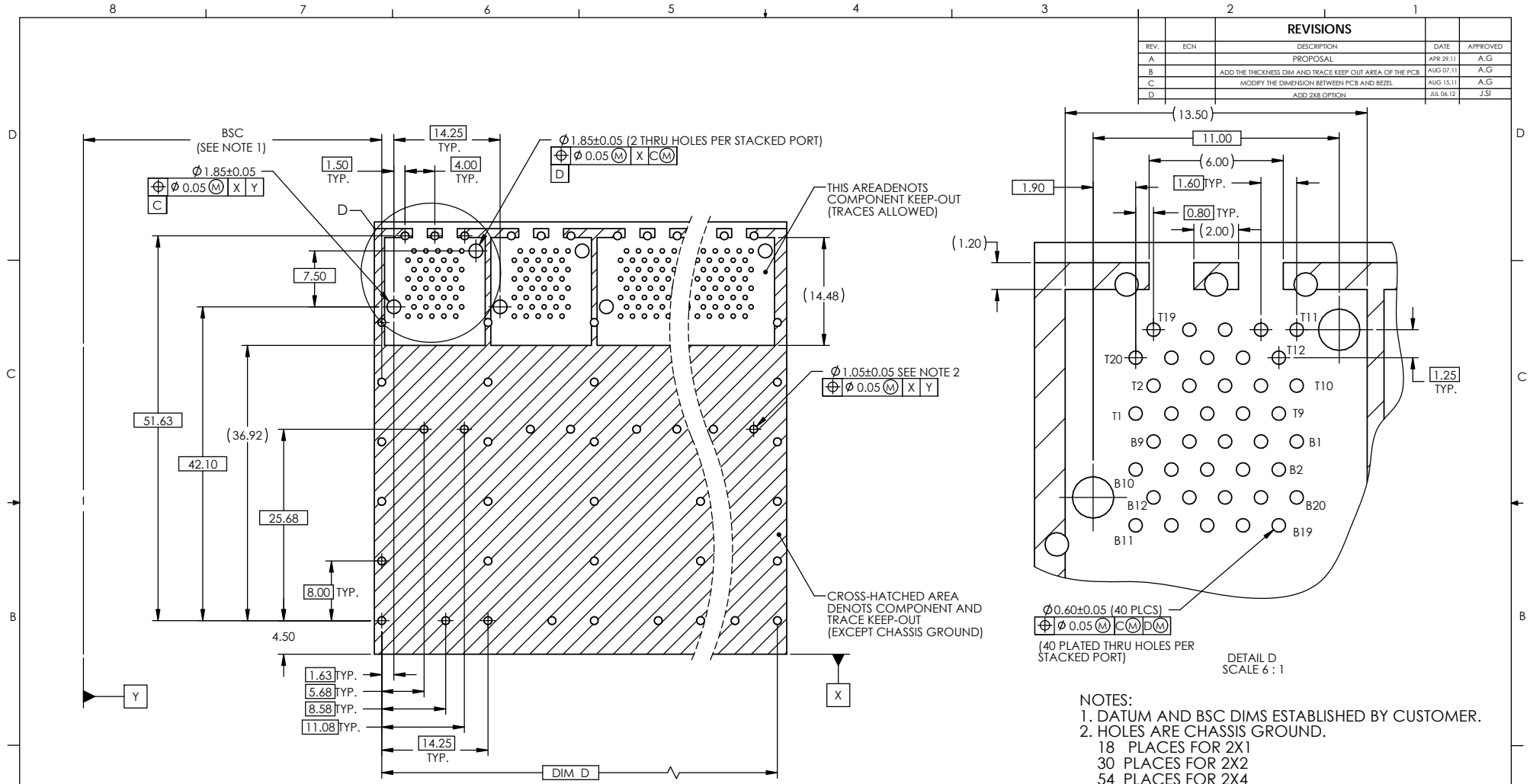
PART NUMBER	DIM A	DIM B
UE78-B1127-00XX1	14.25	16.00
UE78-B2127-00XX1	28.50	30.25
UE78-B4127-00XX1	57.00	58.75
UE78-B5127-00XX1	71.25	73.00
UE78-B6127-00XX1	85.50	87.25
UE78-B8127-00XX1	114.00	115.75

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DECIMALS	ANGLES	DRAWN	MIKE.H	APR 29.11	TITLE		
X.X ± 0.25	± 1°	DESIGNED	J.SI	APR 29.11	SFF 2XN STACKED COMBO WITH DOUBLE BEND LATCH		
X.XX ± 0.15		CHECKED	J.SI	APR 29.11			
MATERIAL AND FINISH		QA APPD					
N/A		E APPD			SIZE	DWG. NO.	REV.
REF.	X				A3	P-UE78-BX127-00XX1	D
CODE IDENT. NO.	03554	DWG APPD	A.GREEN	APR 29.11	SCALE	PROJECT	SHEET
					2:1		2 OF 4

REVISIONS				
REV.	ECN	DESCRIPTION	DATE	APPROVED
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B		ADD THE THICKNESS DIM AND TRACE KEEP OUT AREA OF THE PCB	AUG 07.11	A.G
C		MODIFY THE DIMENSION FROM PCB AND BEZEL	AUG 15.11	A.G
D		ADD 2X8 OPTION	JUL 04.12	J.SI



**RECOMMENDED SFP HOST BOARD LAYOUT
(ONE SIDE CAGE MOUNTING)**

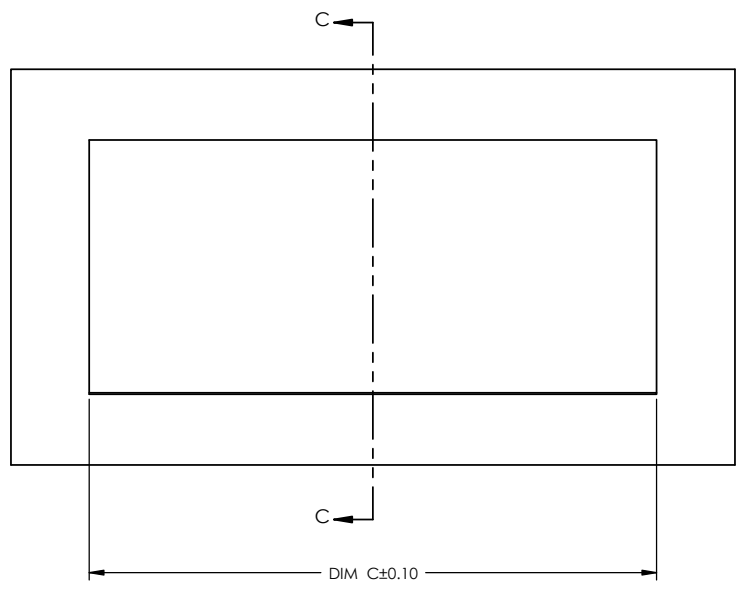
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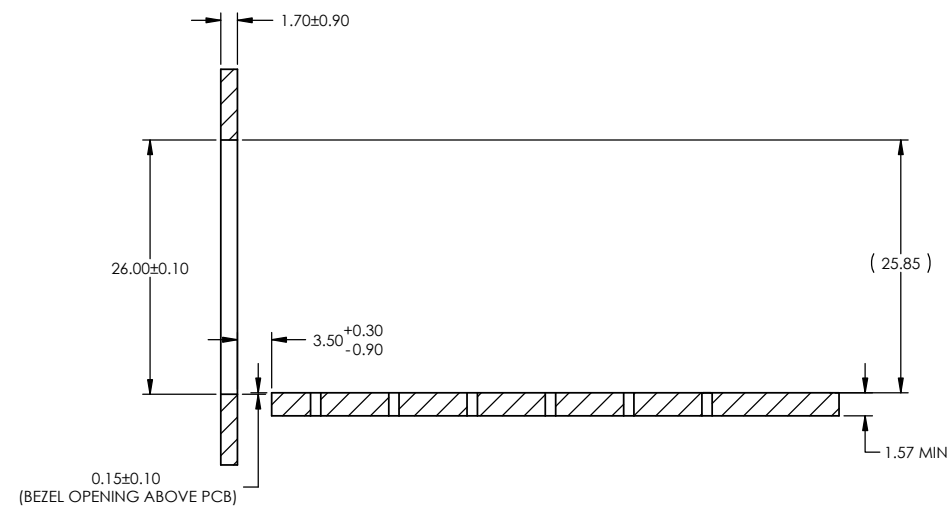
- NOTES:
 1. DATUM AND BSC DIMS ESTABLISHED BY CUSTOMER.
 2. HOLES ARE CHASSIS GROUND.
 18 PLACES FOR 2X1
 30 PLACES FOR 2X2
 54 PLACES FOR 2X4
 66 PLACES FOR 2X5
 78 PLACES FOR 2X6
 102 PLACES FOR 2X8

PART NUMBER		DIM D		UNLESS OTHERWISE SPECIFIED DIMENSIONS ARE IN MILLIMETERS TOLERANCES ARE: DECIMALS ANGLES X.X ± 0.25 ± 1° X.XX ± 0.15	APPROVALS		DATE		Amphenol Canada Corp.		
UE78-B1127-00XX1		14.25			MATERIAL AND FINISH N/A	DRAWN	MIKE.H	APR 29.11		TITLE SFP 2XN STACKED COMBO WITH DOUBLE BEND LATCH	
UE78-B2127-00XX1		28.50		DESIGNED		J.SI	APR 29.11				
UE78-B4127-00XX1		57.00		CHECKED		J.SI	APR 29.11				
UE78-B5127-00XX1		71.25		QA APPD							
UE78-B6127-00XX1		85.50		E APPD							
UE78-B8127-00XX1		114.00		F APPD							
REF.	X	CODE IDENT. NO.	03554	SCALE	2:1	PROJECT	P-UE78-BX127-00XX1	REV.	D	SHEET	3 OF 4

REVISIONS				
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D		ADD 2X8 OPTION	JUL 06.12	J.SI



RECOMMENDED BEZEL DESIGN



SECTION C-C
SCALE 2 : 1

PART NUMBER	DIM C
UE78-B1127-00XX1	15.25
UE78-B2127-00XX1	29.50
UE78-B4127-00XX1	58.00
UE78-B5127-00XX1	72.25
UE78-B6127-00XX1	86.50
UE78-B8127-00XX1	115.00

UNLESS OTHERWISE SPECIFIED DIMENSIONS ARE IN MILLIMETERS TOLERANCES ARE:		APPROVALS		DATE	Amphenol Canada Corp.	
DECIMALS	ANGLES	DRAWN	MIKE.H	APR 29.11	TITLE	
X.X ± 0.25	± 1°	DESIGNED	J.SI	APR 29.11	SFP 2XN STACKED COMBO WITH DOUBLE BEND LATCH	
X.XX ± 0.15		CHECKED	J.SI	APR 29.11		
MATERIAL AND FINISH		QA APPD				
N/A						
REF.		E APPD			SIZE	DWG. NO.
X					A3	P-UE78-BX127-00XX1
CODE IDENT. NO.	03554	DWG APPD	A.GREEN	APR 29.11	SCALE	PROJECT
					2:1	
						SHEET
						4 OF 4

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Данный компонент на территории Российской Федерации

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<http://moschip.ru/get-element>

Вы можете разместить у нас заказ для любого Вашего проекта, будь то серийное производство или разработка единичного прибора.

В нашем ассортименте представлены ведущие мировые производители активных и пассивных электронных компонентов.

Нашей специализацией является поставка электронной компонентной базы двойного назначения, продукции таких производителей как XILINX, Intel (ex.ALTERA), Vicor, Microchip, Texas Instruments, Analog Devices, Mini-Circuits, Amphenol, Glenair.

Сотрудничество с глобальными дистрибьюторами электронных компонентов, предоставляет возможность заказывать и получать с международных складов практически любой перечень компонентов в оптимальные для Вас сроки.

На всех этапах разработки и производства наши партнеры могут получить квалифицированную поддержку опытных инженеров.

Система менеджмента качества компании отвечает требованиям в соответствии с ГОСТ Р ИСО 9001, ГОСТ РВ 0015-002 и ЭС РД 009

Офис по работе с юридическими лицами:

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